



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN#20250709002.2**

**Qualification of RFAB as an additional Fab site option,  
Die Revision, Datasheet & TI Chengdu, TI Philippines as  
additional Assembly & Test site options for select devices  
Change Notification / Sample Request**

**Date:** July 10, 2025

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20250709002.2**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC1G07QDBVRQ1	NULL
SN74LVC1G04QDBVRQ1	SN74LVC1G04QDBVRQ1
SN74LVC1G17QDBVRQ1	SN74LVC1G17QDBVRQ1

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20250709002.2	<b>PCN Date:</b>	July 10, 2025
<b>Title:</b>	Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet & TI Chengdu, TI Philippines as additional Assembly & Test site options for select devices		
<b>Customer Contact:</b>	Change Management Team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	January 06, 2026	<b>Sample requests accepted until:</b>	September 08, 2025*

\*Sample requests received after September 08, 2025 will not be supported.

Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input checked="" type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

### PCN Details

#### Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option & TI Chengdu, TI Philippines as additional Assembly & Test site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter
FFAB	ASLC10/ ASLnonC10	200mm	RFAB	LBC9PLV	300mm

The die was also changed as a result of the process change.

#### Wafer Probe Test:

	Current	Proposed
Wafer probe test	With Probe	No Probe

Construction differences are as follows:

	Current site		Additional site	
Assembly/Test site	UTL2	HFTF	CDAT	PHI
Wire diam/type	1.0mil Au	1.0mil Cu	0.8mil Cu	0.8mil Cu
Mount compound	SID#PZ0001	SID#A-18	4207123	4207123
Mold compound	SID#CZ0096	SID#R-27	4222198	4222198
Lead finish	NiPdAu	NiPdAu	Matte Sn	Matte Sn
Wafer thickness	7.5mil	7.5mil	6.0 mil	6.0 mil

#### Device marking change:

Device name	Old Symbol	New Symbol
SN74LVC1G04QDBVRQ1 SN74LVC1G04QDBVRQ1.A SN74LVC1G04QDBVRQ1.B	34Z5, C040	3NRH, 3VGF
SN74LVC1G07QDBVRQ1 SN74LVC1G07QDBVRQ1.A SN74LVC1G07QDBVRQ1.B	33I5, CCQO	3NPH, 3VQF
SN74LVC1G17QDBVRQ1 SN74LVC1G17QDBVRQ1.A SN74LVC1G17QDBVRQ1.B	34W5, C170	3NQH, 3VRF

The datasheets will be changing as a result of the above mentioned changes. The datasheet

change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

<b>Changes from Revision D (January 2013) to Revision E (June 2025)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Deleted Ordering Information from the front page. See the orderable addendum at the end of the data sheet	1
• Added package sizes to the Device Information table.....	1
• Added ESD Ratings table .....	4
• Added Thermal Information table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 206°C/W to: 357.1°C/W .....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 252°C/W to: 278°C/W .....	5
• Added Application and Implementation section. ....	11
• Added Power Supply Recommendations section. ....	12
• Added Layout section. ....	12

<b>Changes from Revision B (May 2019) to Revision C (June 2025)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed the <i>Device Information</i> table to <i>Package Information</i> .....	1
• Changed Junction-to-ambient thermal resistance value for DBV package from: 269.3°C/W to: 357.1°C/W ....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 175.2°C/W to: 263.7°C/W..	5
• Changed Junction-to-board thermal resistance value for DBV package from: 104.9°C/W to: 264.4°C/W.....	5
• Changed Junction-to-top characterization value for DBV package from: 73.4°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 104.5°C/W to: 262.2°C/W.....	5

<b>Changes from Revision C (January 2020) to Revision D (June 2025)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed <i>Device Information</i> table to <i>Package Information</i> .....	1
• Changed Junction-to-ambient thermal resistance value for DBV package from: 229°C/W to: 357.1°C/W .....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 164°C/W to: 263.7°C/W ....	5
• Changed Junction-to-board thermal resistance value for DBV package from: 62°C/W to: 264.4°C/W .....	5
• Changed Junction-to-top characterization value for DBV package from: 44°C/W to: 195.6°C/W .....	5
• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 262.2°C/W .....	5

<b>Product Folder</b>	<b>Current Datasheet Number</b>	<b>New Datasheet Number</b>	<b>Link to full datasheet</b>
SN74LVC1G04-Q1	SCES482D	<b>SCES482E</b>	<a href="http://www.ti.com/product/SN74LVC1G04-Q1">http://www.ti.com/product/SN74LVC1G04-Q1</a>
SN74LVC1G07-Q1	SCES826B	<b>SCES826C</b>	<a href="http://www.ti.com/product/SN74LVC1G07-Q1">http://www.ti.com/product/SN74LVC1G07-Q1</a>
SN74LVC1G17-Q1	SCES663C	<b>SCES663D</b>	<a href="http://www.ti.com/product/SN74LVC1G17-Q1">http://www.ti.com/product/SN74LVC1G17-Q1</a>

Qual details are provided in the Qual Data Section.

Test coverage, insertions, conditions will remain consistent with current testing.

#### **Reason for Change:**

Supply Continuity

#### **Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

#### **Impact on Environmental Ratings**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental

ratings.

**RoHS**☒ No Change**REACH**☒ No Change**Green Status**☒ No Change**IEC 62474**☒ No Change**Changes to product identification resulting from this PCN:****Fab Site****Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

**Die Rev:****Current****New**

Die Rev [2P]	Die Rev [2P]
A, D, G	<b>A</b>

**Assembly Site Information:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
UTL2	NS2	THA	Bangpakong
HFTF	HFT	CHN	Hefei
<b>TI Chengdu</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>
<b>TI Philippines</b>	<b>PHI</b>	<b>PHL</b>	<b>Baguio city</b>

Sample product shipping label (not actual product label):

**Product Affected:**

SN74LVC1G04QDBVRQ1	SN74LVC1G07QDBVRQ1	SN74LVC1G17QDBVRQ1
SN74LVC1G04QDBVRQ1.A	SN74LVC1G07QDBVRQ1.A	SN74LVC1G17QDBVRQ1.A
SN74LVC1G04QDBVRQ1.B	SN74LVC1G07QDBVRQ1.B	SN74LVC1G17QDBVRQ1.B

## Qualification Report Automotive Qualification Summary

# (As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 19-JUNE -2025

## Product Attributes

Attributes	Qual Device:	Qual Device:	QBS Process Reference:	QBS Package Reference:	QBS Package Reference:	QBS Package Reference:	QBS Package Reference:	QBS Package Reference:
	SN74LVC1G04QDBVRQ1	SN74LVC1G07QDBVRQ1	SN74HCST4QPMRQ1	TPS3840PH30DBVRQ1	SN74AHC1G00DBVRQ1	CAHCT1G14QDBVRQ1	CAHCT1G32QDBVRQ1	SN74LVC1G16DBVRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Logic	Logic	Logic	Power Management	Logic	Logic	Logic	Logic
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB
Assembly Site	CDAT	CDAT	MLA	CDAT	CDAT	CDAT	CDAT	CDAT
Package Group	SOT	SOT	TSSOP	SOT	SOT	SOT	SOT	SOT
Package Designator	DBV	DBV	PW	DBV	DBV	DBV	DBV	DBV
Pin Count	5	5	14	5	5	5	5	5

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74LVC1G04QDBVRQ1 is qualified at MSL1 260C

Qual Device SN74LVC1G07QDBVRQ1 is qualified at MSL1 260C

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: SN74LVC1G04QDBVRQ1	Qual Device: SN74LVC1G07QDBVRQ1	QBS Process Reference: SN74HCST4QPMRQ1	QBS Package Reference: TPS3840PH30DBVRQ1	QBS Package Reference: SN74AHC1G00DBVRQ1	QBS Package Reference: CAHCT1G14QDBVRQ1	QBS Package Reference: CAHCT1G32QDBVRQ1	QBS Product Reference: SN74LVC1G16DBVRQ1
Test Group A - Accelerated Environment Stress Tests															
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	-	3/0/0	3/0/0	1/0/0	1/0/0	1/0/0	1/0/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0
ACU/HAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-	-	-	-
ACU/HAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	-	1/5/0	1/5/0	1/5/0	1/5/0	1/5/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	-	-	-	-	-	1/12/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	3/135/0	-	-	-	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	-	1/45/0	1/45/0	1/45/0	-
Test Group B - Accelerated Lifetime Simulation Tests															
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	3/231/0	3/231/0	-	-	-	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	300 Hours	-	-	-	-	1/77/0	-	-	1/77/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	-	-
Test Group C - Package Assembly Integrity Tests															
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-	3/90/0	3/90/0	1/30/0	1/30/0	1/30/0	1/30/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-	3/90/0	3/90/0	1/30/0	1/30/0	1/30/0	1/30/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	1/15/0	1/15/0	-	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0	1/15/0	-	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	1/10/0	1/10/0	1/10/0	1/10/0
Test Group D - Die Fabrication Reliability Tests															
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDOB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests															
ESD	E2	AEC Q100-002	1	3	ESD HBM	2000 Volts	1/3/0	1/3/0	1/3/0	1/3/0	-	-	-	-	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	500 Volts	1/3/0	1/3/0	1/3/0	1/3/0	-	1/3/0	-	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	3	Lack-Up	Per AEC Q100-004	1/3/0	1/3/0	1/3/0	1/6/0	-	-	-	-	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	1/30/0	1/30/0	3/90/0	3/90/0	1/30/0	1/30/0	1/30/0	1/30/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Texas Instruments Incorporated

TI Information - Selective Disclosure

PCN#20250709002.2

**Ambient Operating Temperature by Automotive Grade Level:**

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD &amp; LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2411-050

## Qualification Report

### Automotive Qualification Summary

#### (As per AEC Q006 and JEDEC Guidelines)

Approve Date 19-JUNE -2025

**Product Attributes**

Attributes	Qual Device: SN74LVC1G04QDBVRQ1	Qual Device: SN74LVC1G07QDBVRQ1	QBS Package Reference: TPS3840PH30DBVRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Logic	Logic	Power Management
Wafer Fab Supplier	RFAB	RFAB	RFAB
Assembly Site	CDAT	CDAT	CDAT
Package Group	SOT	SOT	SOT
Package Designator	DBV	DBV	DBV
Pin Count	5	5	5

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74LVC1G04QDBVRQ1 is qualified at MSL1 260C

Qual Device SN74LVC1G07QDBVRQ1 is qualified at MSL1 260C

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: SN74LVC1G04QDBVRQ1	Qual Device: SN74LVC1G07QDBVRQ1	QBS Reference: TPS3840PH30DBVRQ1
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	-	3/0/0
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	-	-	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	-	-	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	-	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	-	-	3/9/0

HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	-	-	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	-	-	3/9/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	-	-	3/231/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST, 2X	Review for delamination	Completed	-	-	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	-	-	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	-	-	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	-	-	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	-	-	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC, 1X	Review for delamination	Completed	-	-	3/66/0
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	-	-	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	-	-	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	-	-	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	-	-	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	-	-	3/231/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	-	-	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	-	-	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	-	-	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	-	-	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	-	-	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	-	-	3/3/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	-	-	3/135/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	-	-	3/3/0
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-	3/90/0

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-DS-02, SEM-DE-03, SEM-PW-02, SEM-PW-03, SEM-PW-09, SEM-PW-13, SEM-PA-05, SEM-PA-07, SEM-PA-08, SEM-PA-11, SEM-PA-13, SEM-PA-18, SEM-TF-01, SEM-QG-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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